SN74ABT16245A-EP
16-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS

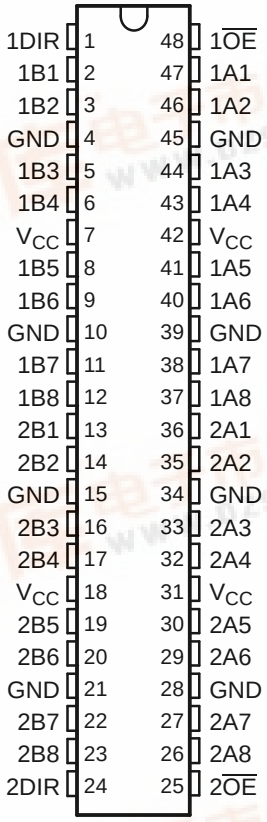
SCBS807B – OCTOBER 2005 – REVISED JANUARY 2006

FEATURES

- **Controlled Baseline**
  - **One Assembly/Test Site, One Fabrication Site**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree** (1)
- **Member of the Texas Instruments Widebus™ Family**
- **State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Typical V_{OLP} (Output Ground Bounce) <1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Latch-Up Performance Exceeds 500 mA Per JESD 70**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Shrink Small-Outline (DL) Package**

(1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

DL PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The SN74ABT16245A-EP is a 16-bit noninverting 3-state transceiver designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so that the buses are effectively isolated.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impendance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT16245A-EP is characterized for operation from –55°C to 125°C.

ORDERING INFORMATION

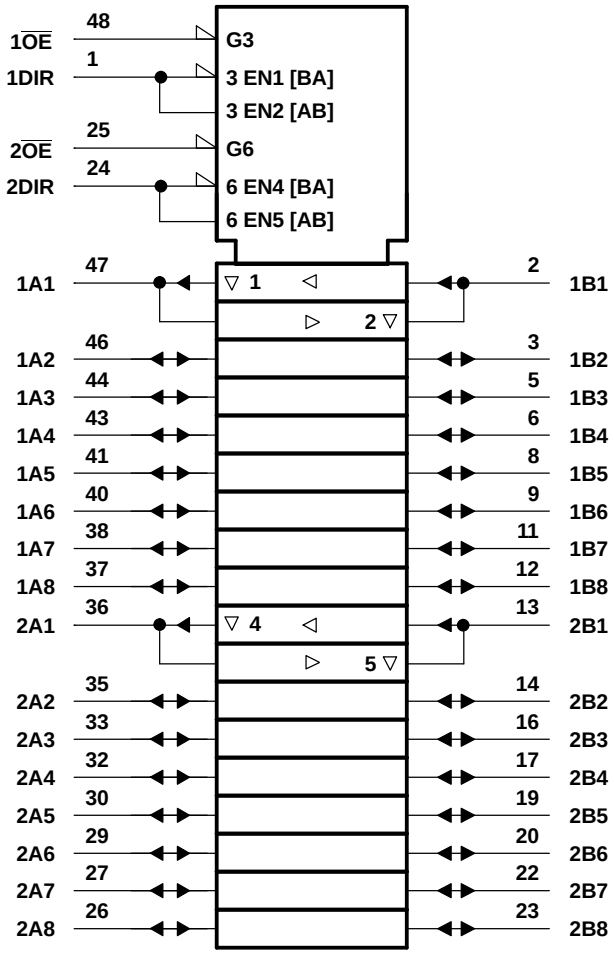
T_A	PACKAGE(1)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	SSOP – DL	Reel of 1000	CABT16245AMDLREP	ABT16245AMEP

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (EACH 8-BIT SECTION)

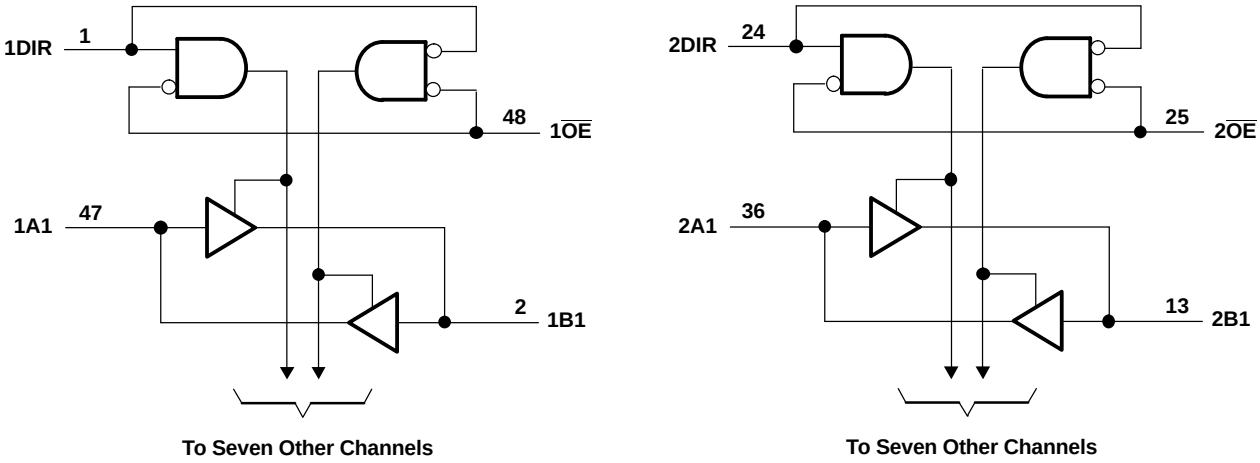
INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

LOGIC SYMBOL(1)



(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	7	V
V_I	Input voltage range (except I/O ports)(2)		–0.5	7	V
V_O	Voltage range applied to any output in the high or power-off state		–0.5	5.5	V
I_O	Current into any output in the low state			96	mA
I_{IK}	Input clamp current	$V_I < 0$		–18	mA
I_{OK}	Output clamp current	$V_O < 0$		–50	mA
θ_{JA}	Package thermal impedance(3)			94	°C/W
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
(3) The package thermal impedance is calculated in accordance with JESD 51.

Recommended Operating Conditions(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		4.5	5.5	V
V_{IH}	High-level input voltage		2		V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage		0	V_{CC}	V
I_{OH}	High-level output current			–24	mA
I_{OL}	Low-level output current			48	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		µs/V
T_A	Operating free-air temperature		–55	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP(1)	MAX			
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2		
			I_{OH} = –32 mA	2					
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55	V
			I_{OL} = 64 mA			0.55			
V_{hys}					100				mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1	µA
	A or B port	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±100	
I_{OZPU}		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			µA
I_{OZPD}		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			µA
I_{OZH}(2)		V_{CC} = 2.7 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10(3)		10	µA
I_{OZL}(2)		V_{CC} = 2.7 V to 5.5 V, V_O = 0.5 V, OE ≥ 2 V				–10(3)		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 5.5 V			±100			µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50	µA
I_O(4)		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	mA
I_{CC}	A or B port	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2	mA
			Outputs low			32		32	
			Outputs disabled			2		2	
ΔI_{CC}(5)	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			2		1.5	mA
			Outputs disabled			0.05		1	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3				pF
C_o	A or B port	V_O = 2.5 V or 0.5 V			6				pF

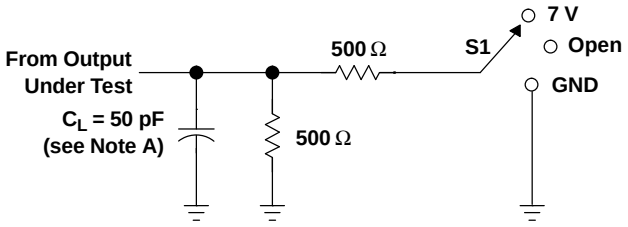
(1) All typical values are at V_{CC} = 5 V.
(2) The parameters I_{OZH} and I_{OZL} include the input leakage current.
(3) This limit may vary among suppliers.
(4) Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
(5) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

Switching Characteristics

over recommended operating ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

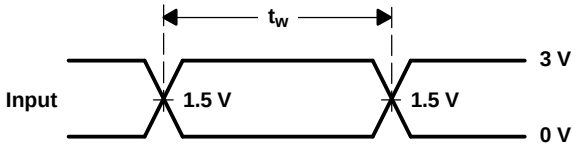
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	0.5	2.2	3.4	0.5	4	ns
t_{PHL}			0.5	2.3	3.8	0.5	4.6	
t_{PZH}	$\overline{OE}$	B or A	0.8	3.6	5.2	0.8	5.5	ns
t_{PZL}			0.9	3.7	6.1	0.1	7.3	
t_{PHZ}	$\overline{OE}$	B or A	1.3	4.4	5.8	1.3	6.3	ns
t_{PLZ}			1.4	3.3	4.7	1.4	5.5	

PARAMETER MEASUREMENT INFORMATION

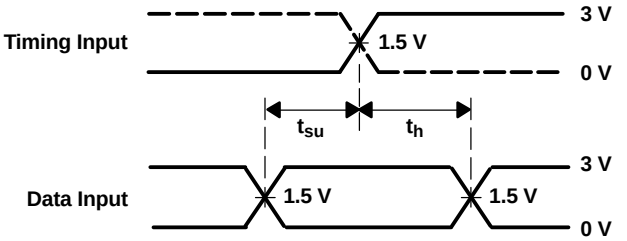


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

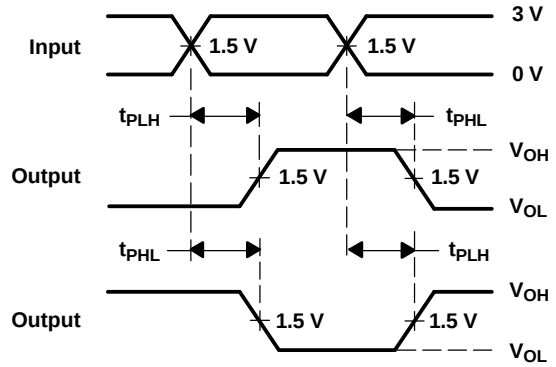
LOAD CIRCUIT



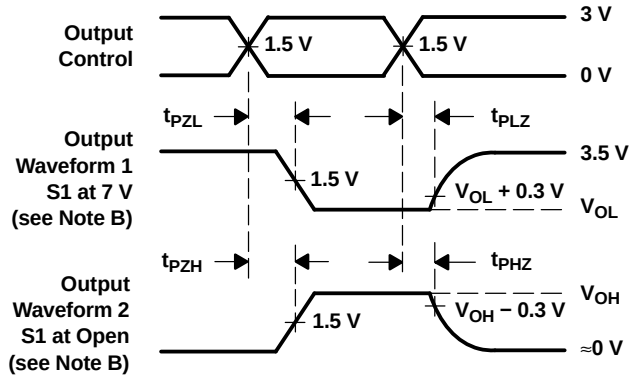
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



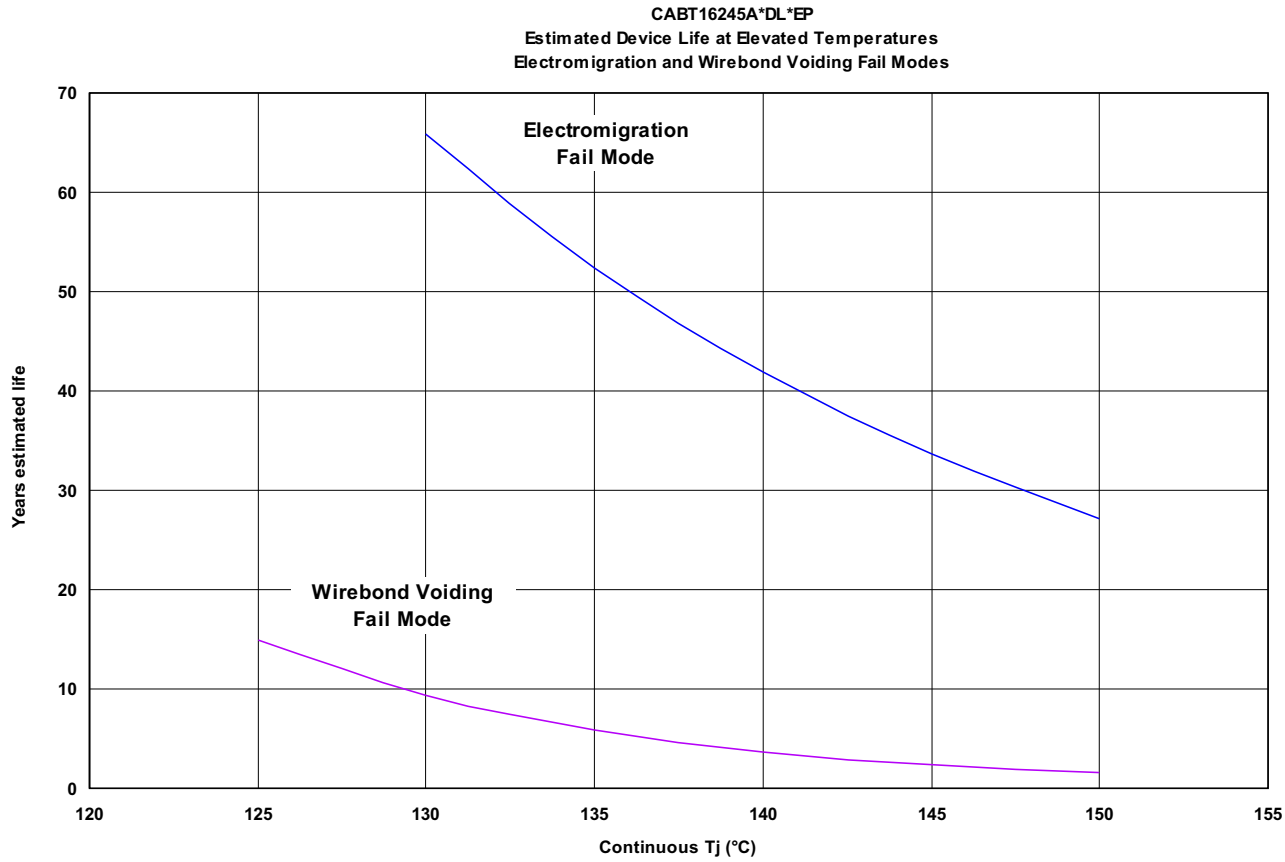
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms


CABT16245A*DL*EP
Estimated Device Life at Elevated Temperatures
Electromigration and Wirebond Voiding Fail Modes
Electromigration
Fail Mode
Wirebond Voiding
Fail Mode
Years estimated life
Continuous Tj (°C)
0
10
20
30
40
50
60
70
120
125
130
135
140
145
150
155

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
CABT16245AMDLREP	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/06609-01XE	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

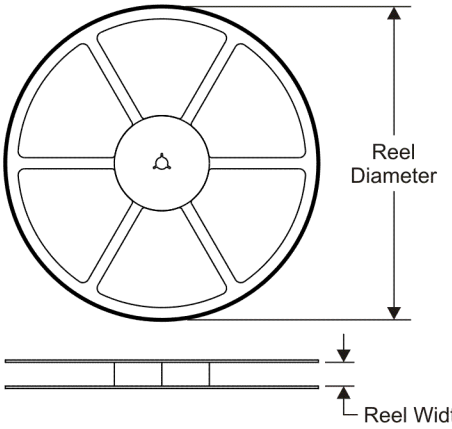
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

OTHER QUALIFIED VERSIONS OF SN74ABT16245A-EP :
- Catalog: SN74ABT16245A
- Military: SN54ABT16245A

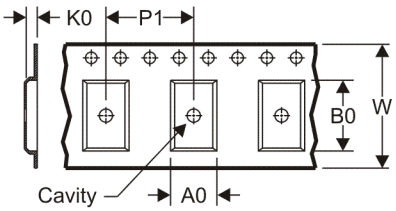
NOTE: Qualified Version Definitions:
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

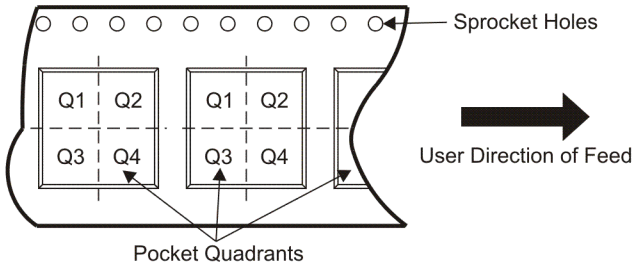


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

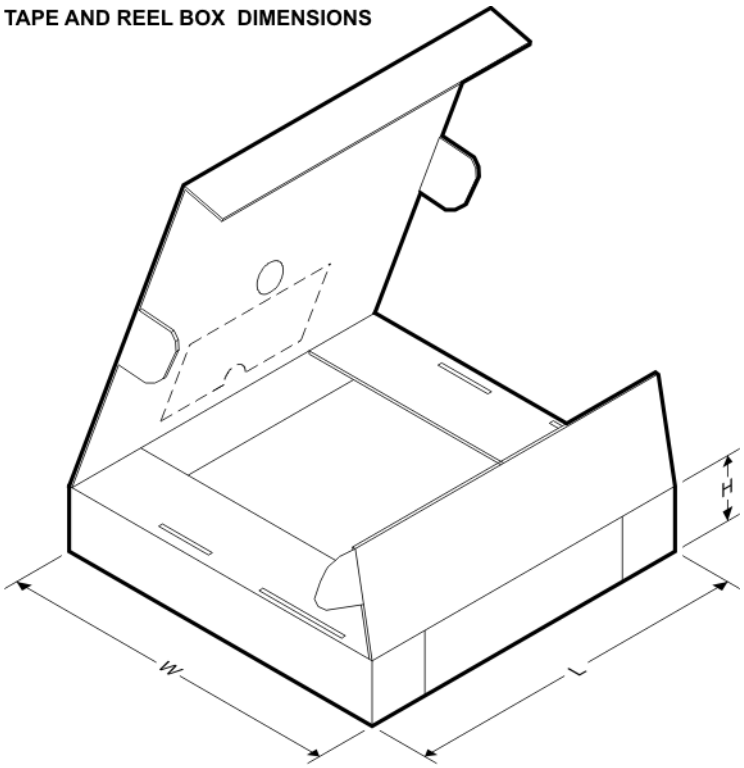
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CABT16245AMDLREP	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CABT16245AMDLREP	SSOP	DL	48	1000	346.0	346.0	49.0

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